

PBGA-SD

Plastic Ball Grid Array - Stacked Die

Highlights

- Stacking of die enables more functionality and integration in a conventional PBGA package



Features

- Increased sub-system performance achieved by integrating multiple chips into a single package
- Die to die bonding capability for device/signal integration
- 15 x 15mm to 40 x 40mm body sizes available
- Ball counts up to >1000 balls
- 0.65, 0.80, 1.00, 1.27 and 1.5mm ball pitch
- SnPb and Pb-free balls available
- Full in-house design capability with wide range of custom and open tool designs
- Full in-house electrical, thermal and mechanical simulation and measurements capability
- Multiple chip design and optional passive/discrete components available
- Standard 2, 4 and 6 layer substrates as well as high density substrate options
- Pb-free and green material set options
- Multiple routing layers and dedicated ground/power planes available for improved electrical and thermal performance

Description

BGA packages can be used for high performance applications with high I/O connections and high thermal and electrical requirements. The characteristics of BGA packages make them suitable for a wide variety of devices used in computing platforms, networking, hand-held consumer products, wireless communications devices, video cameras, home electronic devices and game consoles.

Our chip stack technology offers the flexibility of stacking 2 to 7 die in a single package. The Stacked Die Plastic Ball Grid Array (PBGA-SD) package takes advantage of the proven high electrical and thermal performance of PBGA packages, with efficient use of space made possible through die stacking technology. PBGA-SD packages use laminate substrates and are available in a variety of body sizes and ball counts, combining advanced assembly processes and proven material sets for enhanced yield, reliability and performance.

Applications

- DSPs and Memory
- Gate Arrays
- ASICs
- PC Chipsets and Peripherals
- Microprocessors/Controllers



Specifications

Die Thickness	150-381µm (6-15mils)
Gold Wire	15-30µm (0.6/0.7/0.8/0.9/1.0/1.1/1.2mils) diameter
Pd/Cu Wire	15-30µm (0.6/0.7/0.8/1.0mils) diameter
Bond Pad Pitch	45µm inline or 25/50µm staggered capable
Mold Cap Thickness	0.7-1.17mm
Marking	Laser
Packing Options	JEDEC tray/tape & reel

Reliability

Moisture Sensitivity Level	JEDEC Level 3, 260°C reflow
Temperature Cycling	Condition C (-65°C/150°C), 1000 cycles (typical)
High Temperature Storage	150°C, 1000 hrs (typical)
Pressure Cooker Test	121°C, 100% RH/2 atm, 168 hrs
Temperature/Humidity Test	85°C/85% RH, 1000 hrs
Unbiased HAST	130°C/85%, RH/2 atm, 96 hrs

Thermal Performance θ_{ja} (°C/W)

The thermal performance of each die in the stack is influenced by other die in the stack. Thermal performance is highly dependent on package size, die size, substrate layers and thickness, and solder ball configuration. Simulation for specific applications should be performed.

Electrical Performance

Electrical parasitic data is highly dependent on the package layout. 3D electrical simulation can be used on the specific package design to provide the best prediction of electrical behavior. First order approximations can be calculated using parasitics per unit length for the constituents of the signal path. Data below is for a frequency of 100MHz and assumes 1.0 mil gold bonding wire.

Conductor Component	Length (mm)	Resistance (mOhms)	Inductance (nH)	Inductance Mutual (nH)	Capacitance (pF)	Capacitance Mutual (pF)
Wire	2	120	1.65	0.45 - 0.85	0.10	0.01 - 0.02
Net (2L)	2 - 7	34 - 119	1.3 - 4.55	0.26 - 2.28	0.25 - 0.95	0.06 - 0.42
Total (2L)		154 - 239	2.95 - 6.2	0.71 - 3.13	0.35 - 1.05	0.07 - 0.44
Wire	2	120	1.65	0.45 - 0.85	0.10	0.01 - 0.02
Net (4L)	2 - 7	34 - 119	0.90 - 3.15	0.18 - 1.58	0.35 - 1.10	0.06 - 0.42
Total (4L)		154 - 239	2.55 - 4.80	0.63 - 2.43	0.45 - 1.20	0.07 - 0.44

Note: Net = Total Trace Length + Via + Solder Ball.

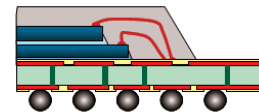
Cross Section

Package Size (mm) Ball Count

15 x 15	160, 176, 196
17 x 17	192, 196, 208, 217, 252, 256
17.2 x 17.2	512
19 x 19	272, 289, 292, 296, 297, 300, 301, 305, 324, 376
21 x 21	400, 456, 484
23 x 23	169, 192, 208, 217, 233, 241, 288, 301, 304, 305, 318, 320, 324, 338, 340, 348, 352, 360, 376, 385, 388, 420, 456, 480, 484, 492
27 x 27	225, 256, 272, 277, 292, 300, 312, 316, 320, 324, 336, 352, 384, 388, 400, 416, 456, 472, 480, 484, 496, 508, 512, 544, 580, 585, 636, 650, 676
31 x 31	304, 320, 353, 385, 421, 433, 434, 448, 458, 460, 480, 540, 556, 560, 564, 604, 608, 609, 640, 644, 652, 676, 688, 692, 701, 721, 772, 896
35 x 35	04, 312, 313, 340, 352, 385, 388, 400, 420, 426, 432, 448, 452, 454, 456, 458, 474, 480, 484, 492, 496, 512, 516, 532, 542, 544, 548, 556, 564, 573, 580, 611, 624, 640, 648, 661, 665, 676, 680, 688, 700, 716, 729, 736, 740, 748, 756, 792, 816, 824, 840, 867, 868, 1012, 1156
37.5 x 37.5	435, 480, 552, 600, 601, 625, 627, 685, 701, 785, 788, 804, 840, 841
40 x 40	503, 557, 569, 596, 600, 745, 776, 928, 961, 1253

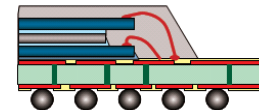
Package Configurations

2 die



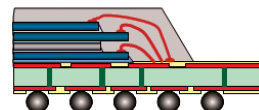
3 die

(2 functional die + 1 spacer die)



4 die

(3 functional die + 1 spacer die)



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